ABSOCIATION CONNECTING LECTRONICS INDUSTRIES® MAterial Comp © Copyright 2005. Il international and Par	PC. Bannock	burn, Illinois, A	Il rights reserved ntions.	under both	This docume level parts, t	ent is a declaration en declaration	on of the su acompasses	bstances v all lower	vithin the manufactu level materials for v	rer listed i which the r	tem. Note: i nanufacture	f the item is an as r has engineering	sembly with lower responsibility.	
	-21.1 IPC Web Site for Information on IPC-1752 Standard For http://www.ipc.org/IPC-175x Di				e * Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				ials and M	als and Mfg Information				
Supplier Information														
Company name*	Company un	Company unique ID			Unique ID Authority				Respon	Response Date*				
onsemi										2024-05	2024-05-09			
Contact Name Title - Contact			tact			Phone - Contact*				Email -	Email - Contact*			
Product-Env-Stewards Product			roduct Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - R			tle - Representative			Phone - Representative*				Email -	Email - Representative*			
Product-Env-Stewards Pro			Product Enviro Compliance			NA				Produc	Product-Env-Stewards@onsemi.com			
Requester Item Number	Mfr Iten	n Number	Mfr Item Name			Effective Date	Version	М	Manufacturing Site		Weight*	UOM	Unit Type	
	NRVUS GA01	NRVUS120VT3G- GA01 REC SMB SPE		CIAL ULTFST		2024-05-09		C	CNP		103.1939	mg	Each	
Manufacturing Proccess Information	tion													
Terminal Plating / Grid Array Ma	terial Terminal Base		Alloy J-STD-020 MSL Ra		Rating	Peak Proce	k Process Body Temperat		ure Max Time at Peak Temper		ure Numb	per of Reflow Cyc	cles	
Matte Tin (Sn) - annealed C		CU Alloy	lloy 1			260	260 C		30 seco		seconds 3			
Comments														
level 1 - maximum time at peak temperatu	re during so	dering is 10-3	0 seconds											
For more information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declar	ation			Declaration Type *	Detailed							
Directive 2015/863/EU amending Rol Directive 2011/65/EU	(Pb), Mercury (Hg), Hexav	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, is of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not ndependently verified information provided by others, Supplier agrees that, at a minimum, itsuppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of hat agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provide												
RoHS Declaration * 4	- Item(s) does not contain RoHS restr	icted substances per the definition	above except for selected exempti	ons Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high meltin Exemption: 7c-I Electrical and elect	g temperature type solders (i.e. lead ronic components containing lead i	l based solder alloys containing n a glass or ceramic other than	85% by weight or more lead). dielectric ceramic in capacitors, o	e.g. piezoelectronic devices, or in a glass or ce	eramic matrix compound.							
Exemption List Version	EL-2011/534/EU											
Declaration Signature												
Instructions: Complete all of the rec Requester) and click on Submit For			Supplier Acceptance drop-down	. This will display the signature area. Digital	ly sign the declaration (if required by the							
Supplier Digital Signature	Rastislav Drska	Le										

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	8.2	mg	Supplier	Iron (Fe)	7439-89-6		0.0082	mg
			Supplier	Copper (Cu)	7440-50-8		8.1893	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0025	mg
Die	0.8039	mg	Supplier	Silicon (Si)	7440-21-3		0.7959	mg
			Supplier	Lead Bisilicate	65997-18-4	7c	0.008	mg
Die Attach Solder	1.62	mg	Supplier	Silver (Ag)	7440-22-4		0.0405	mg
			А	Lead (Pb)	7439-92-1	7a	1.4985	mg
			Supplier	Tin (Sn)	7440-31-5		0.081	mg
Lead Frame	33.6	mg	Supplier	Iron (Fe)	7439-89-6		0.0336	mg
			Supplier	Copper (Cu)	7440-50-8		33.5563	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0101	mg
Mold Compound-Black	55.19	mg	Supplier	Polycondensate of 4,4'- bis(methoxymethyl)biphenyl and phenol	205830-20-2		1.3798	mg
			Supplier	Triphenylphosphine	603-35-0		0.2759	mg
			Supplier	Trimethoxysilylpropanethiol	4420-74-0		0.2759	mg
			Supplier	4,4'-Bis(2,3-epoxypropoxy)-3,3',5,5'- tetramethylbiphenyl	85954-11-6		0.2759	mg
			Supplier	Carbon Black (C)	1333-86-4		0.5519	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		49.671	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		2.7595	mg
Plating	3.78	mg	Supplier	Tin (Sn)	7440-31-5		3.78	mg